

A B S T R A C T

5 The invention relates to a method and a device for bonding solder balls to connecting points which are provided on a substrate in a predetermined pattern. The solder balls are placed into holes provided in a plate-shaped element, which holes are each capable of accommodating one solder ball, and which are provided in the plate-shaped element in a pattern which corresponds with the pattern of the connecting points on the substrate. A combination of at least one substrate and a plate-shaped
10 element containing solder balls is passed, by means of a conveying element, through a housing in which the solder balls are subjected to a heat treatment. The combinations, which each consist of at least one plate-shaped element and at least one substrate, are passed through the housing by the conveying element via lock mechanisms disposed near an inlet and
15 near an outlet of the housing. Inside the housing the solder balls are placed into the holes provided in the plate-shaped element.

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